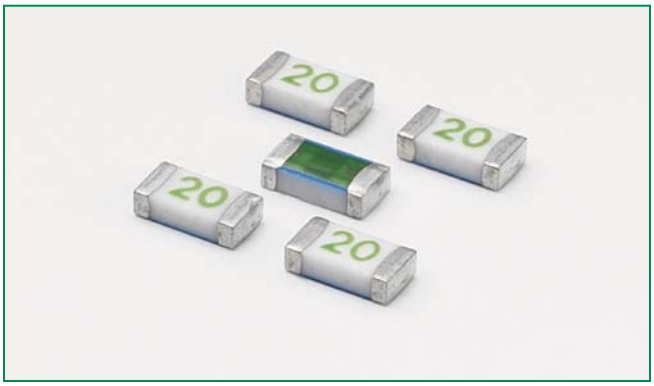
501 Series – High Current 1206 Fast-Acting Fuse



Description

This 100% Lead Free, RoHS compliant and Halogen Free fuse series has been designed specifically to provide over current protection to circuits that see high working ambient temperatures (up to 150°C).

The general design ensures excellent temperature stability and performance reliability.

In addition to this, the high i^2t values typical of the Littelfuse Thin-Film fuse family ensure high inrush current withstand capability.

Agency Approvals

AGENCY	AGENCY FILE NUMBER	AMPERE RANGE
	E10480	15 ~ 20
	E10480	15 ~ 20

Features

- Operating Temperature -55°Cto +150°C
- Designed to provide over current protection in high current voltage regulator module (VRM) applications
- 100% Lead-Free and RoHS compliant
- Suitable for both leaded and lead-free reflow / wave soldering

Electrical Characteristics for Series

% of Ampere Rating	Ampere Rating	Opening Time at 25°C
100%	15A ~ 20A	4 hours Minimum
350%	15A ~ 20A	5 secs. Maximum

Applications

- Voltage Regulator Module (VRM) Equipment

Electrical Specifications by Item

Ampere Rating (A)	Amp Code	Max. Voltage Rating (V)	Interrupt Rating (DC)[1]	Nominal Resistance (Ohms)[2]	Nominal Melting I^2T ($A^2Sec.$)[3]	Nominal Voltage Drop At Rated Current (V)[4]	Nominal Power Dissipation At Rated Current (W)	Agency Approvals	
20A	020.	24	150 A @ 24 V DC	0.002	38.5	0.135	2.70	x	x
15A	015.	24		0.0028	18.5	0.110	1.65	x	x

Notes:

1. DC Interrupt Rating tested at rated voltage with time constant <0.8 msec.
2. Nominal Resistance measured with <10% rated current.
3. Nominal Melting I^2t measured at 1 msec opening time. For other I^2t data refer to chart.
4. Nominal Voltage Drop measured at rated current after temperaturehas stabilized.

Devices designed to carry rated current for 4 hours minimum. It is recommended that devices be operated continuously at no more than 80% rated current. See "Temperature Re-Rating Curve" for additional re-rating information.

Devices designed to be mounted with marking code facing up.

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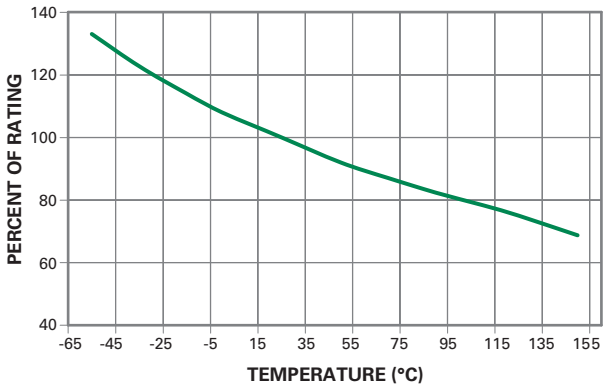
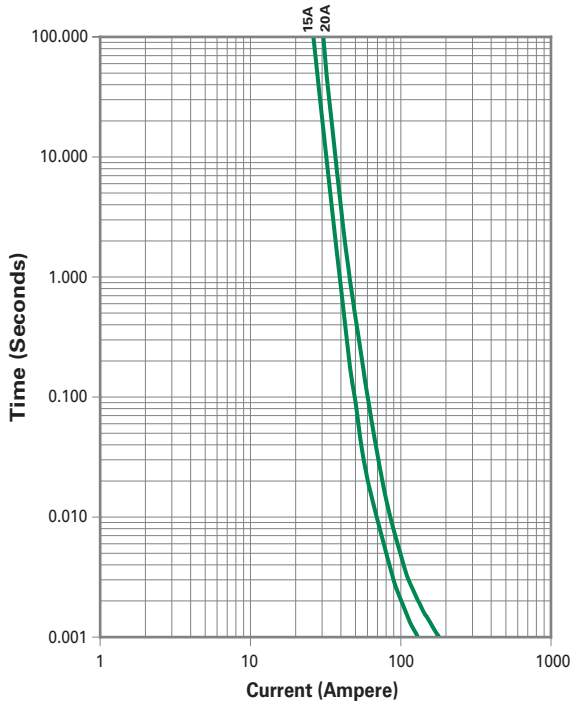
Temperature Rerating Curve



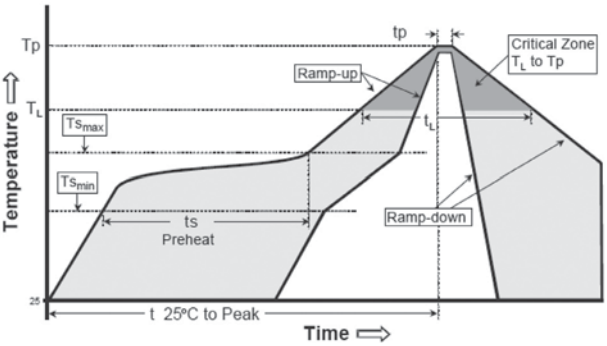
Average Time Current Curves



Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	-Temperature Min ($T_{s(min)}$)	150°C
	-Temperature Max ($T_{s(max)}$)	200°C
	-Time (Min to Max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak		3°C/second max
$T_{S(max)}$ to T_L - Ramp-up Rate		5°C/second max
Reflow	-Temperature (T_L) (Liquidus)	217°C
	-Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		$260^{+0/-5}$ °C
Time within 5°C of actual peak Temperature (t_p)		10 – 30 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		260°C

Wave Soldering	260°C, 10 seconds max.



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Surface Mount Fuses

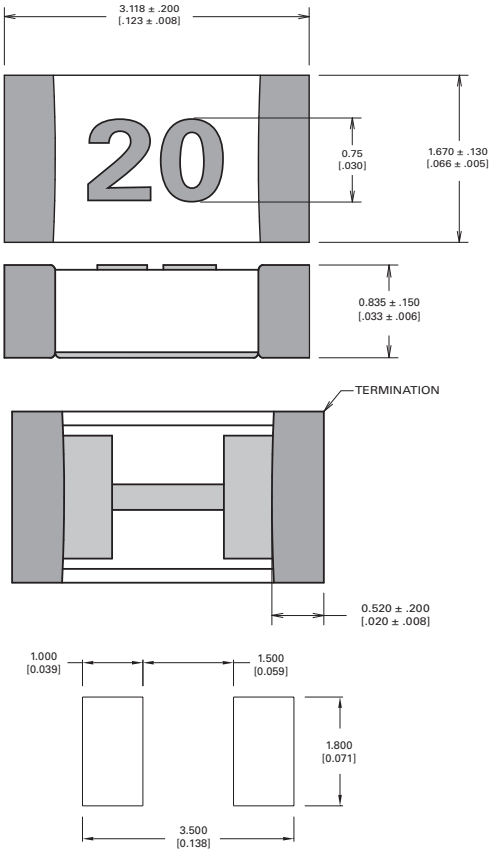
Thin Film High Temperature Fuse > 501 Series

Product Characteristics

Materials	**Body:** Advanced Ceramic **Terminations:** Ag / Ni / Sn (100% Lead-Free) **Element Cover Coating:** Lead-Free Glass
Moisture Sensitivity Level	IPC/JEDEC J-STD-020C, Level 1
Solderability	IPC/EIC/JEDEC J-STD-002B, Condition B
Humidity Test	MIL-STD-202, Method 103B, Conditions D
ESD Immunity	IEC 61000-4-2, 8KV Direct
Resistance to Solvents	MIL-STD-202, Method 210F, Condition B

Moisture Resistance	MIL-STD-202, Method 106G
Thermal Shock	MIL-STD-202, Method 107G, Condition B
Mechanical Shock	MIL-STD-202, Method 213B, Condition A
Vibration	MIL-STD-202, Method 201A
Vibration, High Frequency	MIL-STD-202, Method 204D, Condition D
Dissolution of Metallization	IPC/EIC/JEDEC J-STD-002B, Condition D
Terminal Strength	IEC 60127-4

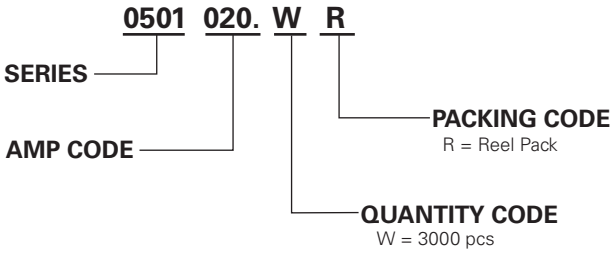
Dimensions



Part Marking System

Amp Code	Marking Code
020.	**20**
015.	**15**

Part Numbering System



Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
8mm Tape and Reel	EIA-481-1 (IEC 286, part 3)	3000	WR

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